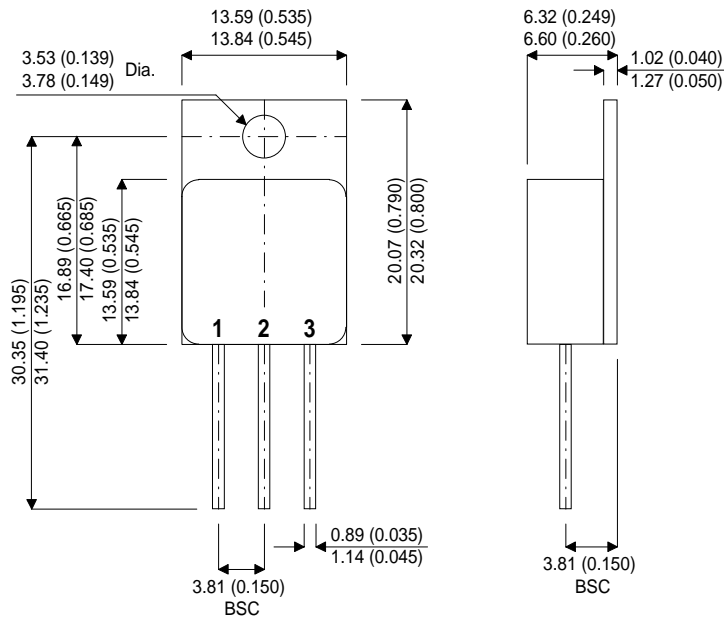


**MECHANICAL DATA**

Dimensions in mm (inches)



**TO-254AA – Isolated Metal Package**

Pin 1 – Drain      Pin 2 – Source      Pin 3 – Gate

**N-CHANNEL  
POWER MOSFET**

$V_{DSS}$       **55V**  
 $I_{D(cont)}$       **35A**  
 $R_{DS(on)}$       **0.015Ω**

**FEATURES**

- N-CHANNEL MOSFET
- HERMETIC ISOLATED TO-254 PACKAGE
- CERAMIC SURFACE MOUNT PACKAGE OPTION

**ABSOLUTE MAXIMUM RATINGS** ( $T_C = 25^\circ C$  unless otherwise stated)

$V_{GS}$	Gate – Source Voltage		±20V
$I_D$	Continuous Drain Current*	@ $V_{GS} = 10V, T_C = 25^\circ C$	35A
		@ $V_{GS} = 10V, T_C = 100^\circ C$	35A
$I_{DM}$	Pulsed Drain Current		140A
$P_D$	Max. Power Dissipation	@ $T_C = 25^\circ C$	125W
	Linear Derating Factor		1.0W / °C
$I_L$	Avalanche Current, Clamped <sup>1</sup>		35A
dv / dt	Peak Diode Recovery <sup>2</sup>		2.6V / ns
$R_{\theta JC}$	Thermal Resistance Junction – Case		1.0°C / W
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range		-55 to 150°C
$T_L$	Lead Temperature (1.6mm from case for 10s)		300°C

1) Repetitive Rating: Pulse width limited by Max. Junction Temperature.  
 2)  $I_{SD} \leq 35A, di/dt \leq 230A / \mu S, V_{DD} \leq BV_{DSS}, T_J \leq 150^\circ C$

Semelab Plc reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing orders.

<b>ELECTRICAL CHARACTERISTICS</b> ( $T_J = 25^\circ\text{C}$ unless otherwise stated)						
Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
<b>STATIC ELECTRICAL RATINGS</b>						
$BV_{DSS}$	Drain – Source Breakdown Voltage	$V_{GS} = 0$ $I_D = 250\mu\text{A}$	55			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Temperature Coefficient of Breakdown Voltage	Reference to $25^\circ\text{C}$ $I_D = 1\text{mA}$		0.056		V/ $^\circ\text{C}$
$R_{DS(on)}$	Static Drain – Source On–State Resistance <sup>2</sup>	$V_{GS} = 10\text{V}$ $I_D = 35\text{A}$			0.015	$\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ $I_D = 250\mu\text{A}$	2		4	V
$g_{fs}$	Forward Transconductance <sup>2</sup>	$V_{DS} \geq 15\text{V}$ $I_{DS} = 35\text{A}$	34			S( $\bar{r}$ )
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 55\text{V}$ $V_{GS} = 0$			25	$\mu\text{A}$
		$V_{DS} = 44\text{V}$ $T_J = 125^\circ\text{C}$			250	
$I_{GSS}$	Forward Gate – Source Leakage	$V_{GS} = 20\text{V}$			100	nA
$I_{GSS}$	Reverse Gate – Source Leakage	$V_{GS} = -20\text{V}$			-100	
<b>DYNAMIC CHARACTERISTICS</b>						
$C_{iss}$	Input Capacitance	$V_{GS} = 0$		3600		pF
$C_{oss}$	Output Capacitance	$V_{DS} = 25\text{V}$		1200		
$C_{rss}$	Reverse Transfer Capacitance	$f = 1\text{MHz}$		445		
$Q_g$	Total Gate Charge	$V_{GS} = 10\text{V}$			170	nC
$Q_{gs}$	Gate – Source Charge	$I_D = 35\text{A}$			32	
$Q_{gd}$	Gate – Drain (“Miller”) Charge	$V_{DS} = 44\text{V}$			74	
$t_{d(on)}$	Turn– On Delay Time	$V_{DD} = 28\text{V}$			22	ns
$t_r$	Rise Time	$I_D = 35\text{A}$			80	
$t_{d(off)}$	Turn–Off Delay Time	$R_G = 2.5\Omega$			70	
$t_f$	Fall Time	$V_{GS} = 10\text{V}$			55	
<b>SOURCE – DRAIN DIODE CHARACTERISTICS</b>						
$I_S$	Continuous Source Current (Body)				35	A
$I_{SM}$	Pulse Source Current <sup>1</sup>				140	
$V_{SD}$	Diode Forward Voltage	$I_S = 35\text{A}$ $V_{GS} = 0$			1.3	V
$t_{rr}$	Reverse Recovery Time <sup>3</sup>	$I_F = 35\text{A}$ $T_J = 25^\circ\text{C}$			130	ns
$Q_{rr}$	Reverse Recovery Charge <sup>3</sup>	$d_i / d_t \leq 100\text{A}/\mu\text{s}$ $V_{DD} \leq 25\text{V}$			410	nC
$t_{on}$	Forward Turn–On Time			Negligible		